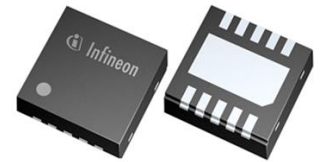


Ultra low quiescent current linear voltage regulator

Features

- Ultra low quiescent current of 5 μ A
- Wide input voltage range of 2.75 V to 42 V
- Output current capacity up to 100 mA
- Low drop out voltage of typ. 200 mV @ 100 mA
- Output current limit protection
- Overtemperature shutdown
- Available in PG-TSON-10 package
- Wide temperature range
- Green Product (RoHS-compliant)
- AEC Qualified



Potential applications

- Applications with direct battery connection
- Automotive general ECUs
- On-board sensor supply
- Infotainment, alarm, dashboard
- RKE, immobilizer, gateway

Product validation

Qualified for automotive applications.

Product validation according to AEC-Q100.

Description

The TLS810A1 is a linear voltage regulator featuring wide input voltage range, low drop out voltage and ultra low quiescent current.

With an input voltage range of 2.75 V to 42 V and ultra low quiescent of only 5 μ A, the regulator is perfectly suitable for automotive or any other supply systems connected permanently to the battery.

The OPTIREG™ linear TLS810A1LDV50 is the fixed 5 V output version with an accuracy of 2% and output current capability up to 100 mA.

The new regulation concept implemented in TLS810A1 combines fast regulation and very good stability while requiring only a small ceramic capacitor of 1 μ F at the output.

The tracking region starts already at input voltages of 2.75 V (extended operating range). This makes the TLS810A1 also suitable to supply automotive systems that need to operate during cranking condition.

Internal protection features like output current limitation and overtemperature shutdown are implemented to protect the device against immediate damage due to failures like output short circuit to GND, overcurrent and overtemperature.

Choosing external components

An input capacitor C_I is recommended to compensate line influences. The output capacitor C_O is necessary for the stability of the regulating circuit. Stability is specified at values $C_O \geq 1 \mu$ F and an $ESR \leq 100 \Omega$ within the whole operating range.

Type	Package	Marking
TLS810A1LDV50	PG-TSON-10	810A1V5

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1 Block diagram

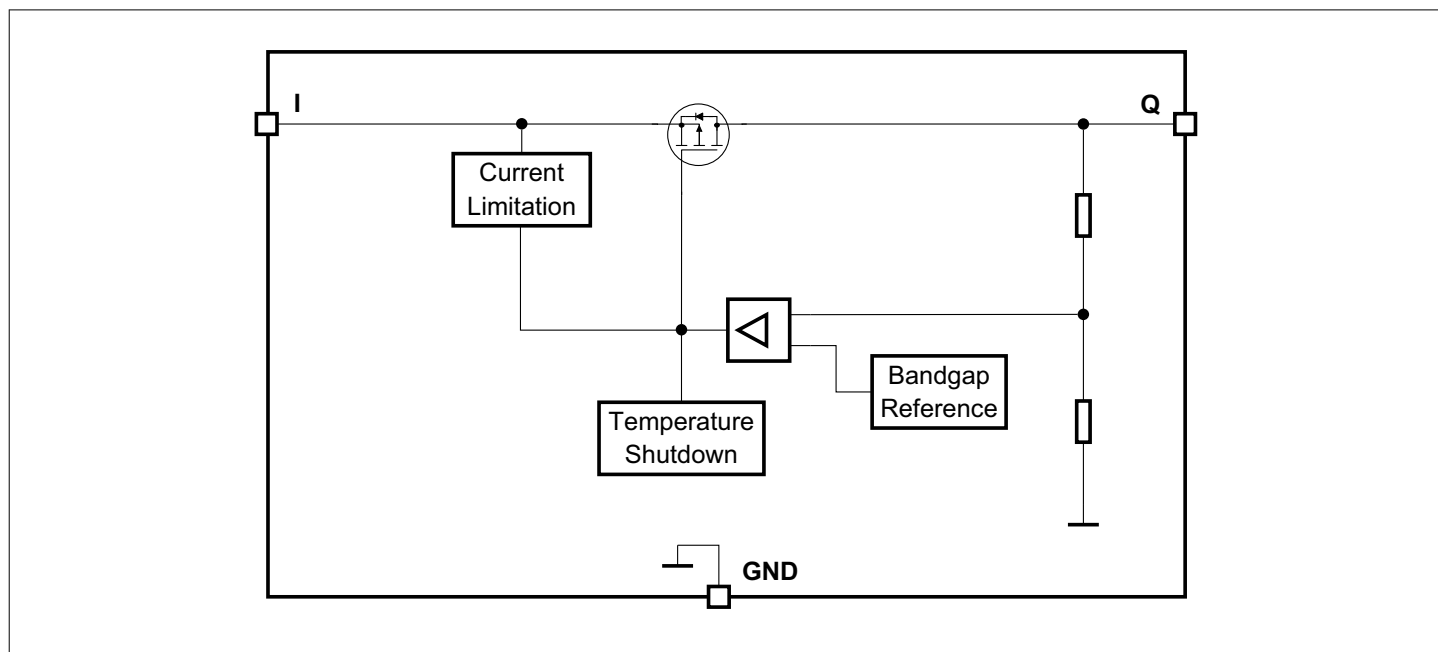


Figure 1 Block diagram

2 Pin configuration

2.1 Pin assignment in PG-TSON-10 package

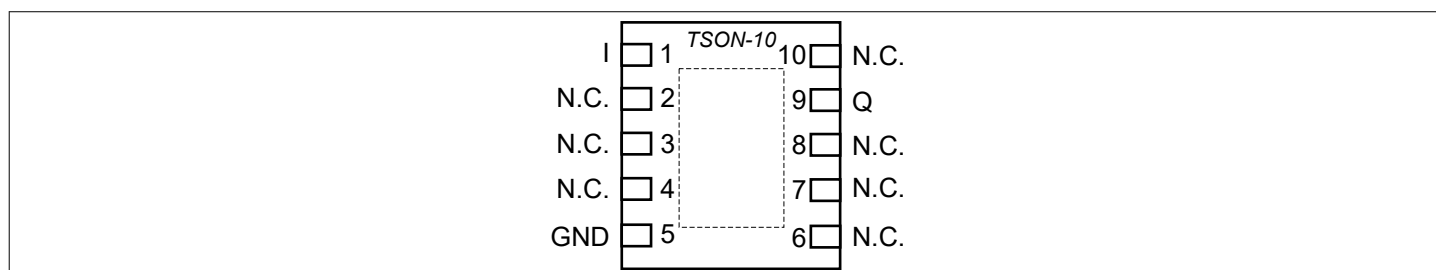


Figure 2 Pin configuration

2.2 Pin definitions and functions

Table 1 Pin definitions and functions

Pin	Symbol	Function
1	I	Input It is recommended to place a small ceramic capacitor (for example 100 nF) to GND, close to the IC terminals, in order to compensate line influences.
2	N.C.	Not connected
3	N.C.	Not connected
4	N.C.	Not connected
5	GND	Ground
6	N.C.	Not connected
7	N.C.	Not connected
8	N.C.	Not connected
9	Q	Output Connect an output capacitor C_Q to GND close to the IC's terminals, respecting the values specified for its capacitance and ESR in Functional range .
10	N.C.	Not connected
Pad	–	Exposed pad Connect to heatsink area. Connect to GND.

3 General product characteristics

3.1 Absolute maximum ratings

Table 2 Absolute maximum ratings ¹⁾

$T_j = -40^\circ\text{C}$ to $+150^\circ\text{C}$; all voltages with respect to ground (unless otherwise specified)

Parameter	Symbol	Values			Unit	Note or Test Condition	Number
		Min.	Typ.	Max.			
Voltage input I							
Voltage	V_I	-0.3	–	45	V	–	P_4.1.1
Voltage output Q							
Voltage	V_Q	-0.3	–	7	V	–	P_4.1.2
Temperatures							
Junction temperature	T_j	-40	–	150	°C	–	P_4.1.3
Storage temperature	T_{stg}	-55	–	150	°C	–	P_4.1.4
ESD robustness							
ESD robustness all pins (HBM)	$V_{ESD,HBM}$	-2	–	2	kV	²⁾	P_4.1.5
ESD robustness all pins (CDM)	$V_{ESD,CDM}$	-750	–	750	V	³⁾ at all pins	P_4.1.6

1) Not subject to production test, specified by design.

2) ESD robustness, Human Body Model (HBM) according to ANSI/ESDA/JEDEC JS001 (1.5 kΩ, 100 pF)

3) ESD robustness, Charged Device Model (CDM) according JEDEC JESD22-C101

Notes:

1. Stresses above the ones listed here may cause permanent damage to the device. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.
2. Integrated protection functions are designed to prevent IC destruction under fault conditions described in the data sheet. Fault conditions are considered as “outside” normal operating range. Protection functions are not designed for continuous repetitive operation.

3.2 Functional range

Note: Within the functional or operating range, the IC operates as described in the circuit description. The electrical characteristics are specified within the conditions given in the Electrical Characteristics table.

Table 3 Functional range

Parameter	Symbol	Values			Unit	Note or Test Condition	Number
		Min.	Typ.	Max.			
Input voltage range	V_I	$V_{Q,nom} + V_{dr}$	–	42	V	1)	P_4.2.1
Extended input voltage range	$V_{I,ext}$	2.75	–	42	V	2)	P_4.2.2
Output capacitor	C_Q	1	–	–	μF	3) 4)	P_4.2.3
Output capacitor's ESR	$ESR(C_Q)$	–	–	100	Ω	4)	P_4.2.4
Junction temperature	T_j	-40	–	150	°C	–	P_4.2.5

1) Output current is limited internally and depends on the input voltage, see Electrical characteristics for more details.

2) When V_I is between $V_{I,ext,min}$ and $V_{Q,nom} + V_{dr}$, $V_Q = V_I - V_{dr}$. When V_I is below $V_{I,ext,min}$, V_Q can drop down to 0 V.

3) The minimum output capacitance requirement is applicable for a worst case capacitance tolerance of 30%.

4) Not subject to production testing, specified by design.

3.3 Thermal resistance

Note: This thermal data was generated in accordance with JEDEC JESD51 standards. For more information, go to www.jedec.org.

Table 4 Thermal resistance TLS810A1 in PG-TSON-10 package¹⁾

Parameter	Symbol	Values			Unit	Note or Test Condition	Number
		Min.	Typ.	Max.			
Junction to case	R_{thJC}	–	13	–	K/W	–	P_4.3.1
Junction to ambient	R_{thJA}	–	60	–	K/W	²⁾ 2s2p board	P_4.3.2
Junction to ambient	R_{thJA}	–	184	–	K/W	³⁾ 1s0p board, footprint only	P_4.3.3
Junction to ambient	R_{thJA}	–	75	–	K/W	³⁾ 1s0p board, 300 mm ² heatsink area on PCB	P_4.3.4
Junction to ambient	R_{thJA}	–	64	–	K/W	³⁾ 1s0p board, 600 mm ² heatsink area on PCB	P_4.3.5

1) Not subject to production test, specified by design

2) Specified R_{thJA} value is according to JEDEC JESD51-2,-5,-7 at natural convection on FR4 2s2p board. The product (chip and package) was simulated on a 76.2 × 114.3 × 1.5 mm³ board with 2 inner copper layers (2 × 70 μm Cu, 2 × 35 μm Cu). Where applicable a thermal via array under the exposed pad contacted the first inner copper layer.

3) Specified R_{thJA} value is according to JEDEC JESD 51-3 at natural convection on FR4 1s0p board. The product (chip and package) was simulated on a 76.2 × 114.3 × 1.5 mm³ board with 1 copper layer (1 × 70 μm Cu).

4 Block description and electrical characteristics

4.1 Voltage regulation

The output voltage V_Q is divided by a resistor network. This fractional voltage is compared to an internal voltage reference and the pass transistor is driven accordingly.

The control loop stability depends on the output capacitor C_Q , the load current, the chip temperature and the internal circuit structure. To ensure stable operation, the output capacitor's capacitance and its equivalent series resistance ESR requirements given in [Functional range](#) have to be maintained. For details see the typical performance graph [Output capacitor equivalent series resistance ESR \(\$C_Q\$ \) versus output current \$I_Q\$](#) . Since the output capacitor is used to buffer load steps, it should be sized according to the application's needs.

An input capacitor C_I is not required for stability, but is recommended to compensate line fluctuations. An additional reverse polarity protection diode and a combination of several capacitors for filtering should be used, in case the input is connected directly to the battery line. Connect the capacitors close to the regulator terminals.

In order to prevent overshoots during start-up, a smooth ramping up function is implemented. This ensures almost no overshoots during start-up, mostly independent from load and output capacitance.

Whenever the load current exceeds the specified limit, for example in case of a short circuit, the output current is limited and the output voltage decreases.

The overtemperature shutdown circuit prevents the IC from immediate destruction under fault conditions (for example output continuously short-circuit) by switching off the power stage. After the chip has cooled down, the regulator restarts. This oscillatory thermal behavior causes the junction temperature to exceed the maximum rating of 150°C and can significantly reduce the IC's lifetime.

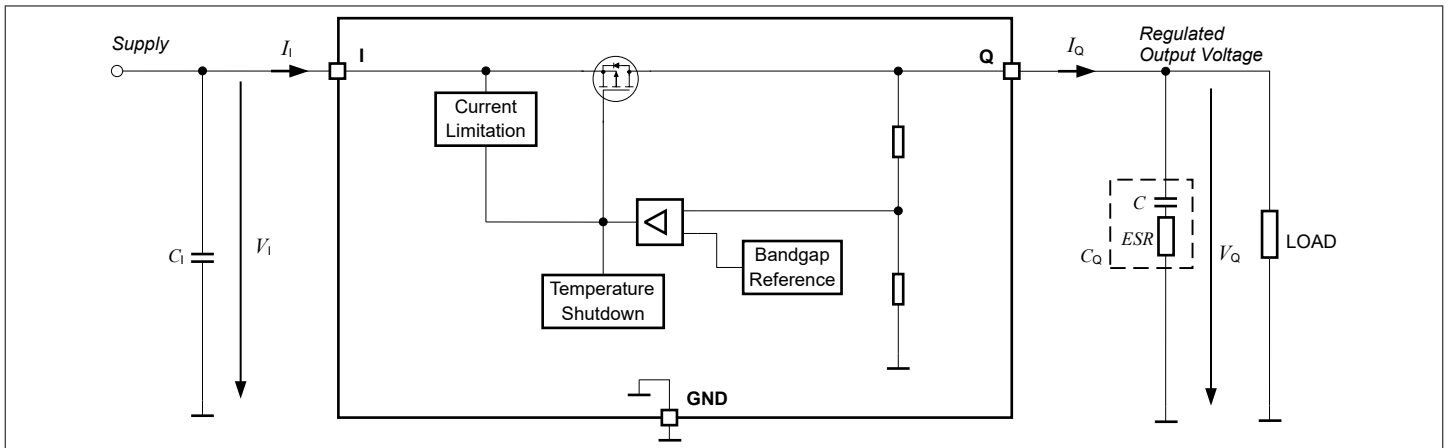


Figure 3 Block diagram voltage regulation

4 Block description and electrical characteristics

Table 5 Electrical characteristics

$T_j = -40^\circ\text{C}$ to $+150^\circ\text{C}$, $V_I = 13.5\text{ V}$, all voltages with respect to ground (unless otherwise specified).

Typical values are given at $T_j = 25^\circ\text{C}$, $V_I = 13.5\text{ V}$.

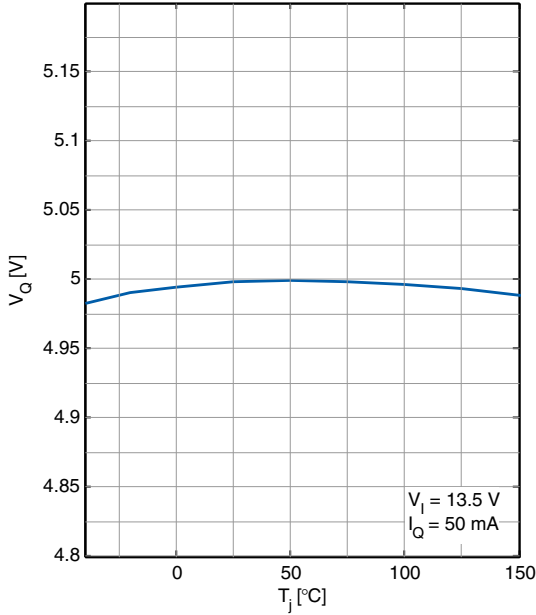
Parameter	Symbol	Values			Unit	Note or Test Condition	Number
		Min.	Typ.	Max.			
Output voltage precision	V_Q	4.90	5.00	5.10	V	$50\ \mu\text{A} \leq I_Q \leq 100\ \text{mA}$, $5.7\ \text{V} \leq V_I \leq 28\ \text{V}$	P_5.1.1
Output voltage precision	V_Q	4.90	5.00	5.10	V	$50\ \mu\text{A} \leq I_Q \leq 50\ \text{mA}$, $5.7\ \text{V} \leq V_I \leq 42\ \text{V}$	P_5.1.2
Output current limitation	$I_{Q,lim}$	110	190	260	mA	$0\ \text{V} \leq V_Q \leq V_{Q,nom} - 0.1\ \text{V}$	P_5.1.3
Line regulation steady-state	$\Delta V_{Q,line}$	–	1	20	mV	$I_Q = 1\ \text{mA}$, $6\ \text{V} \leq V_I \leq 32\ \text{V}$	P_5.1.4
Load regulation steady-state	$\Delta V_{Q,load}$	-20	-1	–	mV	$V_I = 6\ \text{V}$, $50\ \mu\text{A} \leq I_Q \leq 100\ \text{mA}$	P_5.1.5
Dropout voltage $V_{dr} = V_I - V_Q$	V_{dr}	–	200	550	mV	¹⁾ $I_Q = 100\ \text{mA}$	P_5.1.6
Ripple rejection	$PSRR$	–	55	–	dB	²⁾ $I_Q = 50\ \text{mA}$, $f_{ripple} = 100\ \text{Hz}$, $V_{ripple} = 0.5\ V_{p-p}$	P_5.1.7
Overtemperature shutdown threshold	$T_{j,sd}$	151	175	–	$^\circ\text{C}$	²⁾ T_j increasing	P_5.1.8
Overtemperature shutdown threshold hysteresis	$T_{j,sdh}$	–	10	–	K	²⁾ T_j decreasing	P_5.1.9

1) Measured when the output voltage V_Q has dropped 100 mV from the nominal value obtained at $V_I = 13.5\text{ V}$.

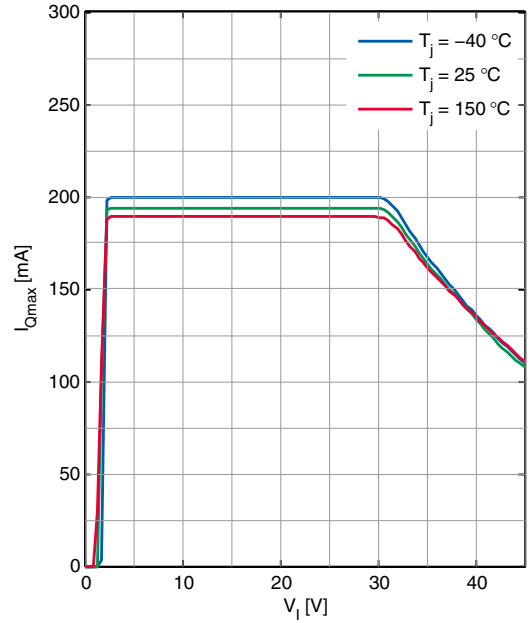
2) Not subject to production test, specified by design.

4.2 Typical performance characteristics voltage regulation

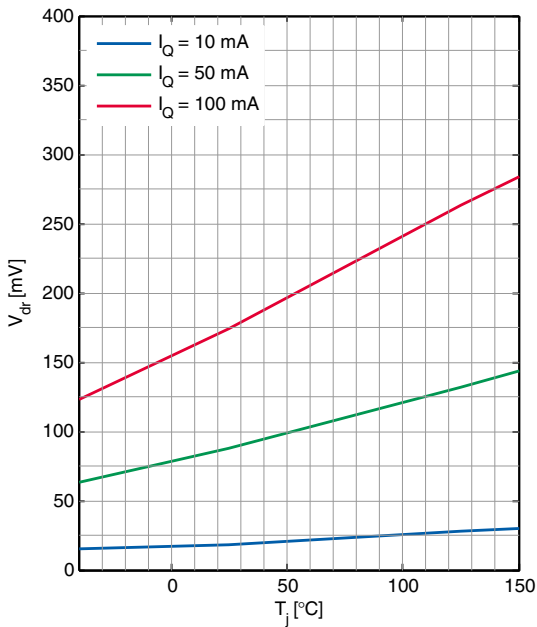
Output voltage V_Q versus junction temperature T_j



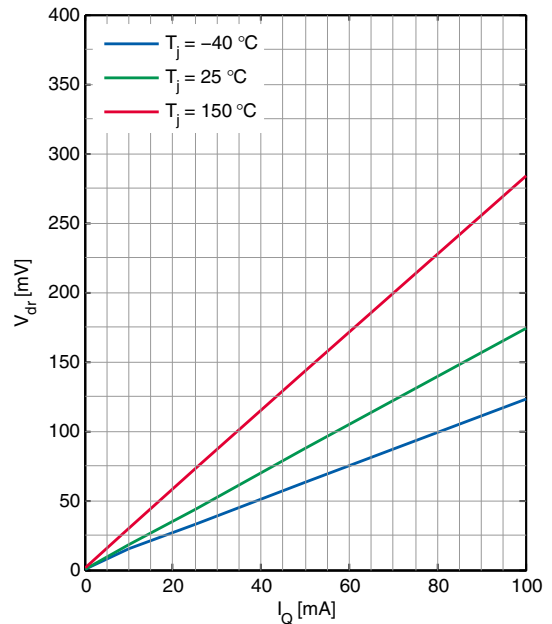
Output current I_{Qmax} versus input voltage V_I



Dropout voltage V_{dr} versus junction temperature T_j

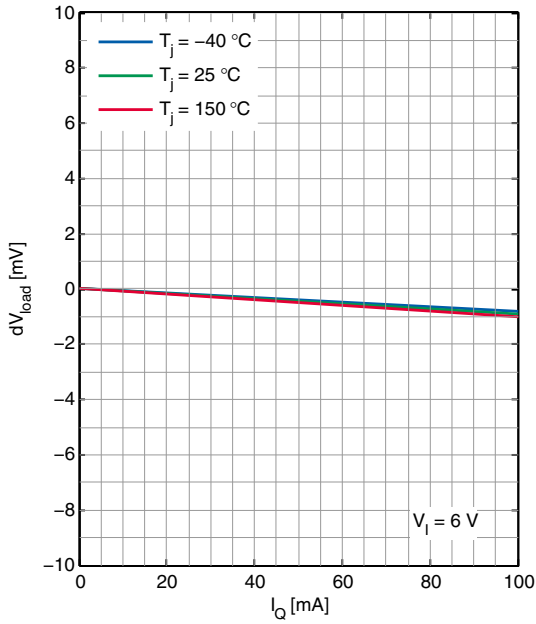


Dropout voltage V_{dr} versus output current I_Q

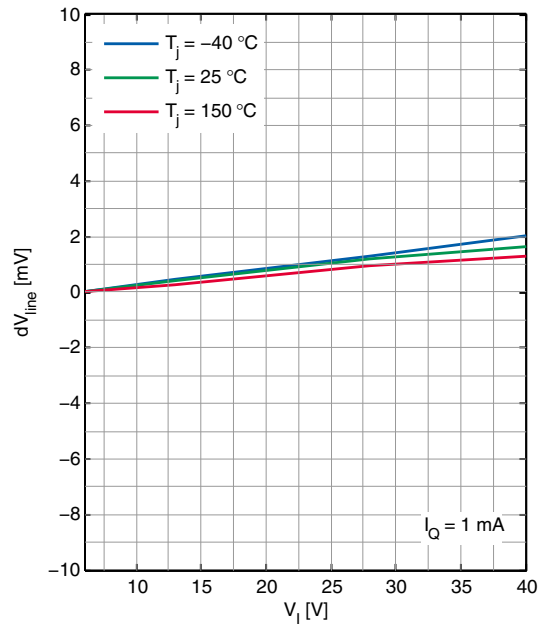


4 Block description and electrical characteristics

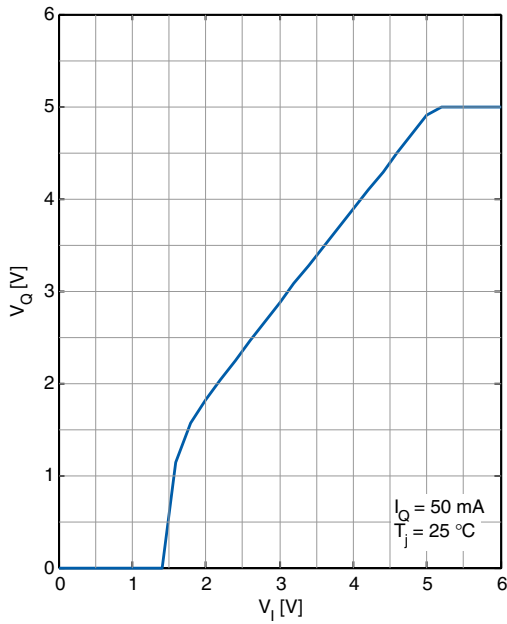
Load regulation $\Delta V_{Q,load}$ versus output current I_Q



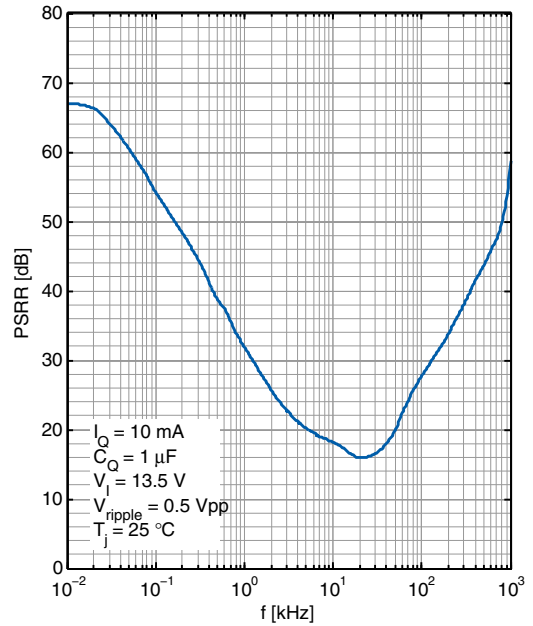
Line regulation $\Delta V_{Q,line}$ versus input voltage V_1



Output voltage V_Q versus input voltage V_1

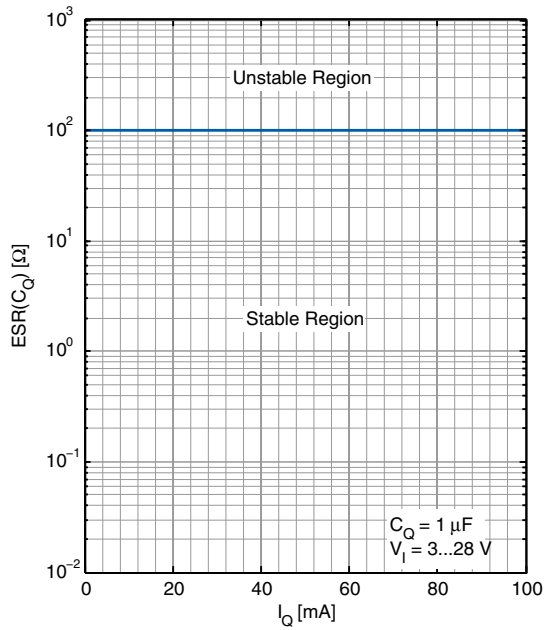


Power supply ripple rejection $PSRR$ versus ripple frequency f_r



4 Block description and electrical characteristics

Output capacitor equivalent series resistance $ESR(C_Q)$
versus output current I_Q



4.3 Current consumption

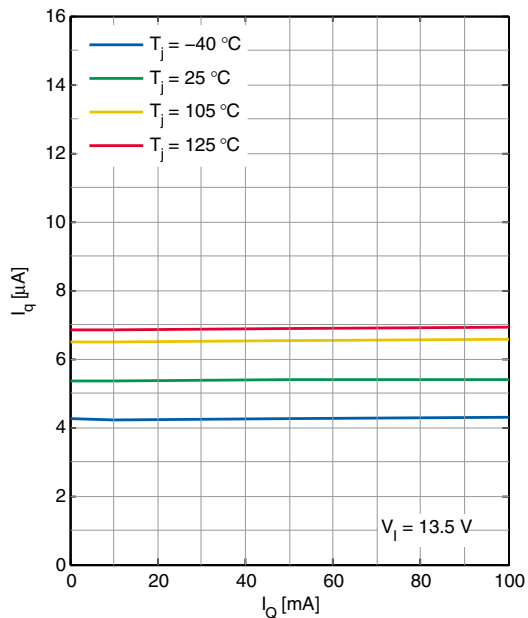
Table 6 Electrical characteristics current consumption

$T_j = -40^\circ\text{C}$ to $+150^\circ\text{C}$, $V_I = 13.5\text{ V}$ (unless otherwise specified).

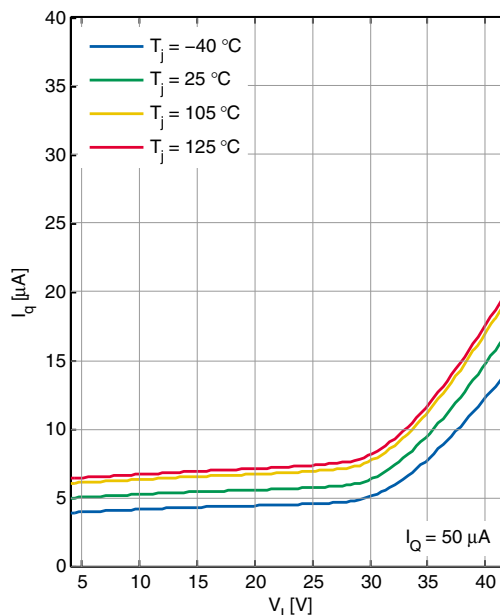
Parameter	Symbol	Values			Unit	Note or Test Condition	Number
		Min.	Typ.	Max.			
Current consumption $I_q = I_I - I_Q$	I_q	–	5	7.5	μA	$I_Q = 50\ \mu\text{A}$, $T_j = 25^\circ\text{C}$	P_5.3.1
Current consumption $I_q = I_I - I_Q$	I_q	–	6.5	10	μA	$I_Q = 50\ \mu\text{A}$, $T_j < 105^\circ\text{C}$	P_5.3.2
Current consumption $I_q = I_I - I_Q$	I_q	–	7	11	μA	$I_Q = 50\ \mu\text{A}$, $T_j < 125^\circ\text{C}$	P_5.3.3
Current consumption $I_q = I_I - I_Q$	I_q	–	7	11	μA	$I_Q = 100\ \text{mA}$, $T_j < 125^\circ\text{C}$	P_5.3.4

4.4 Typical performance characteristics current consumption

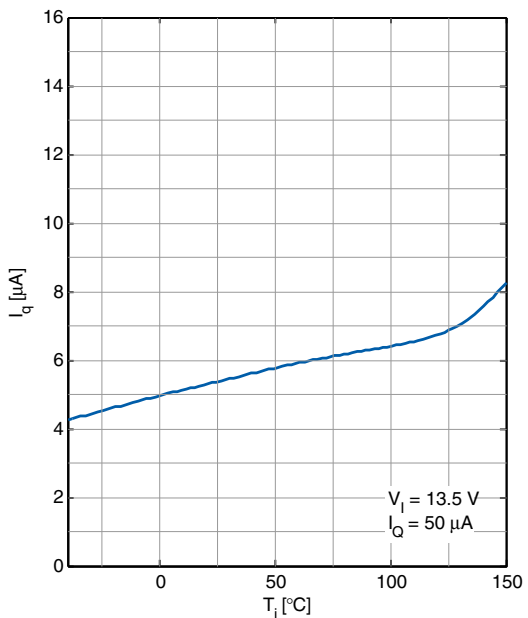
Current consumption I_q versus
 Output current I_Q



Current consumption I_q versus
 Input voltage V_i



Current consumption I_q versus
 Junction temperature T_j



In case of rapid transients of input voltage or load current, the capacitance should be dimensioned in accordance and verified in the real application that the output stability requirements are fulfilled.

5.3 Thermal considerations

Knowing the input voltage, the output voltage and the load profile of the application, the total power dissipation can be calculated:

$$P_D = (V_I - V_Q) \times I_Q + V_I \times I_q \quad (1)$$

with

- P_D : continuous power dissipation
- V_I : input voltage
- V_Q : output voltage
- I_Q : output current
- I_q : quiescent current

The maximum acceptable thermal resistance R_{thJA} can then be calculated:

$$R_{thJA, \max} = \frac{T_{j, \max} - T_a}{P_D} \quad (2)$$

with

- $T_{j, \max}$: maximum allowed junction temperature
- T_a : ambient temperature

Based on the above calculation the proper PCB type and the necessary heat sink area can be determined with reference to the specification in [Thermal resistance](#).

Example

Application conditions:

$$V_I = 13.5 \text{ V}$$

$$V_Q = 5 \text{ V}$$

$$I_Q = 80 \text{ mA}$$

$$T_a = 105^\circ\text{C}$$

Calculation of $R_{thJA, \max}$:

$$P_D = (V_I - V_Q) \times I_Q + V_I \times I_q$$

$$= (13.5 \text{ V} - 5 \text{ V}) \times 80 \text{ mA} + 13.5 \text{ V} \times 0.016 \text{ mA}$$

$$= 0.68 \text{ W}$$

$$R_{thJA, \max} = (T_{j, \max} - T_a) / P_D$$

$$= (150^\circ\text{C} - 105^\circ\text{C}) / 0.68 \text{ W}$$

$$= 66.2 \text{ K/W}$$

As a result, the PCB design must ensure a thermal resistance R_{thJA} lower than 66.2 K/W. According to [Thermal resistance](#) at least 600 mm² heatsink area is needed on the FR4 1s0p PCB, or the FR4 2s2p board can be used.

5.4 Reverse polarity protection

TLS810A1 is not self protected against reverse polarity faults. To protect the device against negative supply voltage, an external reverse polarity diode is needed, as shown in [Figure 4](#). The absolute maximum ratings of the device as specified in [Chapter 3.1](#) must be respected.

5.5 Further application information

For further information you may contact <http://www.infineon.com>

6 Package outlines

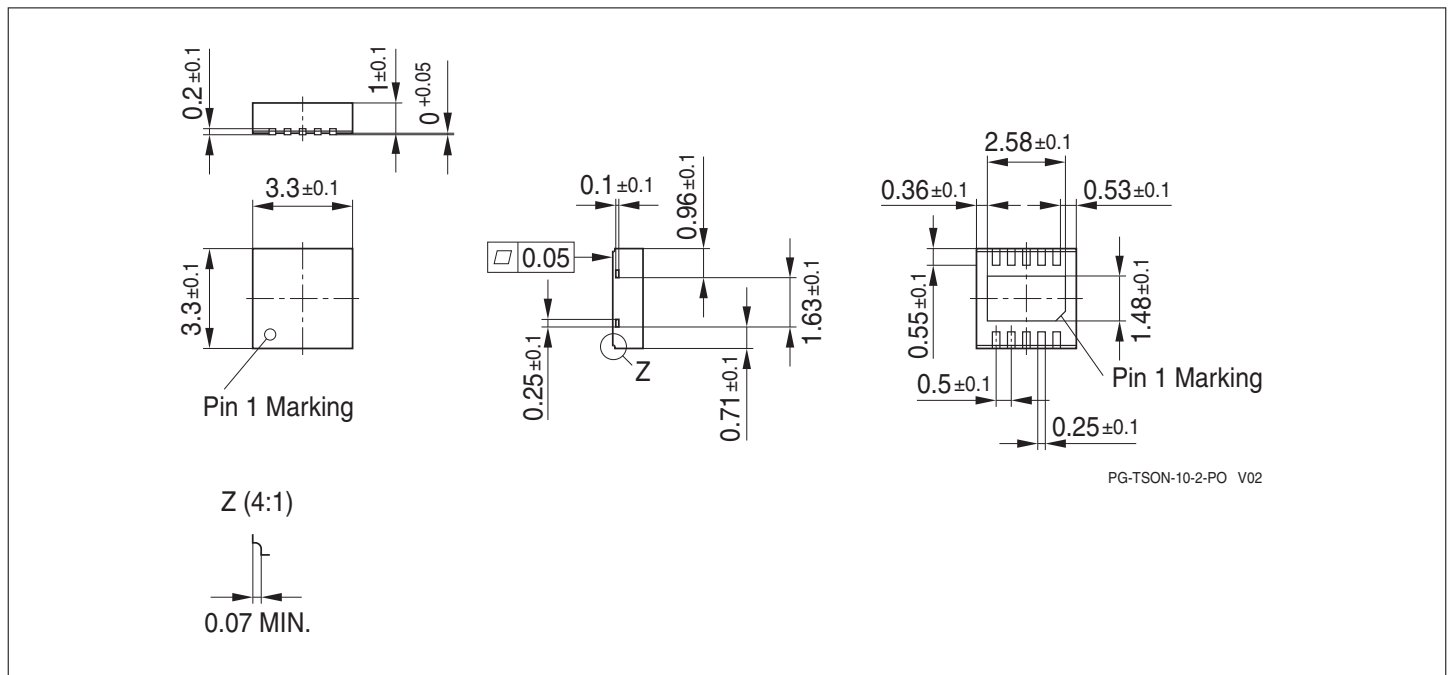


Figure 5 PG-TSON-10 ¹⁾

Green product (RoHS-compliant)

To meet the world-wide customer requirements for environmentally friendly products and to be compliant with government regulations the device is available as a green product. Green products are RoHS-compliant (Pb-free finish on leads and suitable for Pb-free soldering according to IPC/JEDEC J-STD-020).

For further information on alternative packages, please visit our website: www.infineon.com/packages

¹⁾ Dimensions in mm

7 Revision History

Revision	Date	Changes
1.01	2025-02-07	Editorial changes and template update P-numbers of section 4.3. unified from P_5.2.x to P_5.3.x
1.00	2016-03-15	Datasheet - Initial version

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